

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

What is claimed is:

1. (Previously Presented) A negative-type photosensitive resin composition comprising an epoxy compound, poly(*p*-vinylphenol) and a phenol-biphenylene resin.
2. Cancelled.
3. (Previously Presented) The negative-type photosensitive resin composition of claim 1, wherein the phenol-biphenylene resin is present in the range of 5 – 45 weight % based on the total weight of poly(*p*-vinylphenol) and phenol-biphenylene resin.
4. (Original) Method for the formation of a resist pattern, comprising the steps of coating the negative-type photosensitive resin composition of claim 1 on a substrate; exposing the resin composition; and developing of the exposed composition to form the resist pattern.
5. (Previously Presented) The method of claim 4, wherein the developing comprises contacting the exposed composition with an aqueous alkaline solution.
6. (Previously Presented) The method of claim 4, wherein the exposing comprises exposing the resin composition to actinic radiation.
7. (Previously Presented) The negative-type photosensitive resin composition of claim 1, wherein the composition is developable in an aqueous alkaline solution.
8. (New) The negative-type photosensitive resin composition of claim 1, further comprising an alkoxyalkylated melamine.
9. (New) The method of claim 4, wherein the negative-type photosensitive resin composition further comprises an alkoxyalkylated melamine.